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WET TIME ETCHING

ABSTRACT

The invention relates to a system and method for etching micro electromechanical wafers including an etch bath arranged to contain a wafer holder and a mixture of etchant and deionised water, sensor means arranged to determine when the level of liquid in the etch bath falls below a predetermined level, a deionised water feeder arranged to provide deionised water to the etch bath, rotation means arranged to rotate the wafer holder about a horizontal axis, wherein the wafer holder is arranged to accommodate a plurality of wafers in a row with space between the wafers.

Figure 1

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